



Description

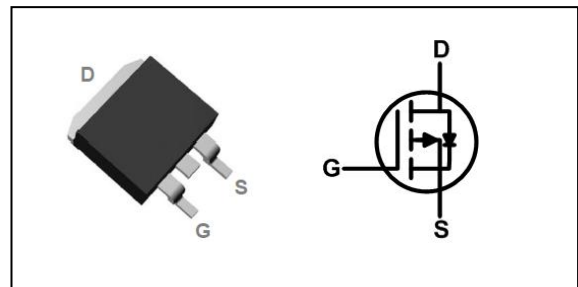
The HSH100P06 is the high cell density trench P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The HSH100P06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Product Summary

| | | |
|------------------|------|----|
| V_{DS} | -60 | V |
| $R_{DS(ON),typ}$ | 7.0 | mΩ |
| I_D | -100 | A |

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

TO-263 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|------------------------|--|------------|-------|
| V_{DS} | Drain-Source Voltage | -60 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D@T_C=25^{\circ}C$ | Continuous Drain Current, $-V_{GS} @ -10V^1$ | -100 | A |
| $I_D@T_C=100^{\circ}C$ | Continuous Drain Current, $-V_{GS} @ -10V^1$ | -70 | A |
| I_{DM} | Pulsed Drain Current ² | -280 | A |
| EAS | Single Pulse Avalanche Energy ³ | 310 | mJ |
| I_{AS} | Avalanche Current | 100 | A |
| $P_D@T_C=25^{\circ}C$ | Total Power Dissipation ⁴ | 210 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 62 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 0.71 | °C/W |



Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|------------------------------|--|---|------|--------|-----------|---------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -60 | --- | --- | V |
| $\Delta BV_{DSS}/\Delta T_J$ | BV_{DSS} Temperature Coefficient | Reference to 25°C , $I_D=-1\text{mA}$ | --- | -0.036 | --- | $V/^\circ\text{C}$ |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=-10V, I_D=-20A$ | --- | 7.0 | 8 | $m\Omega$ |
| | | $V_{GS}=-4.5V, I_D=-10A$ | --- | 8.5 | 10 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=-250\mu A$ | -1.0 | -1.65 | -2.5 | V |
| $\Delta V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | | --- | 4.28 | --- | $mV/^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=-48V, V_{GS}=0V, T_J=25^\circ\text{C}$ | --- | --- | 1 | μA |
| | | $V_{DS}=-48V, V_{GS}=0V, T_J=55^\circ\text{C}$ | --- | --- | 10 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| gfs | Forward Transconductance | $V_{DS}=-10V, I_D=-3A$ | --- | 15 | --- | S |
| Q_g | Total Gate Charge | $V_{DS}=-30V, V_{GS}=-10V, I_D=-5A$ | --- | 195 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 26 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 45 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=-48V, V_{GS}=-10V, R_G=6\Omega, I_D=-1A$ | --- | 26 | --- | ns |
| T_r | Rise Time | | --- | 36 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 290 | --- | |
| T_f | Fall Time | | --- | 88 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=-30V, V_{GS}=0V, f=1\text{MHz}$ | --- | 13320 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 510 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 469 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|--|--|------|------|------|------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | -100 | A |
| I_{SM} | Pulsed Source Current ^{2,5} | | --- | --- | -280 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$ | --- | --- | -1 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=-50V, V_{GS}=-10V, L=0.1\text{mH}, R_G=25\Omega, I_{AS}=-100A$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

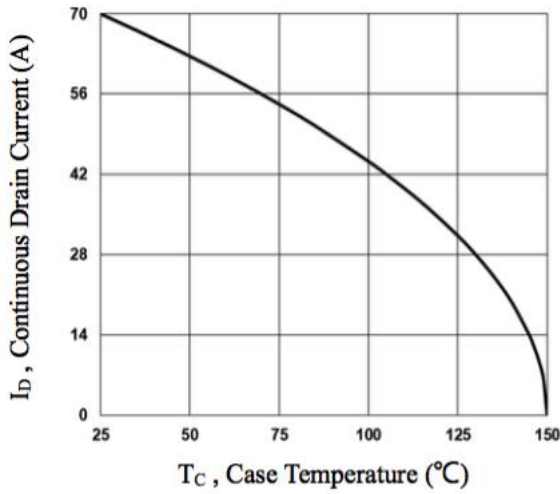


Fig.1 Continuous Drain Current vs. T_C

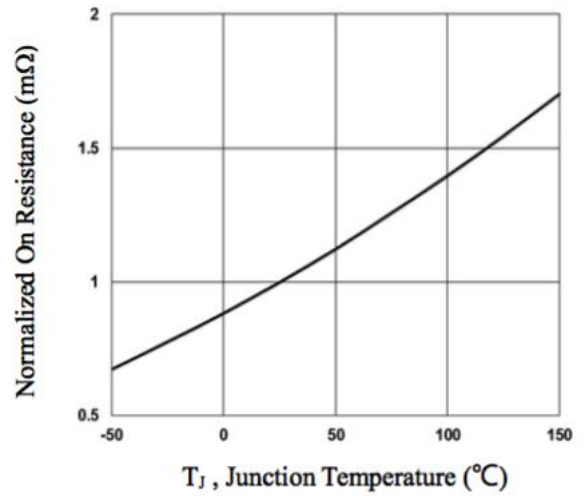


Fig.2 Normalized $R_{DS(on)}$ vs. T_J

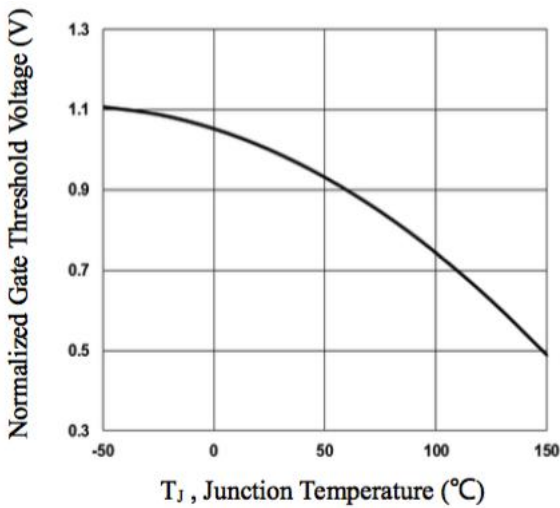


Fig.3 Normalized V_{th} vs. T_J

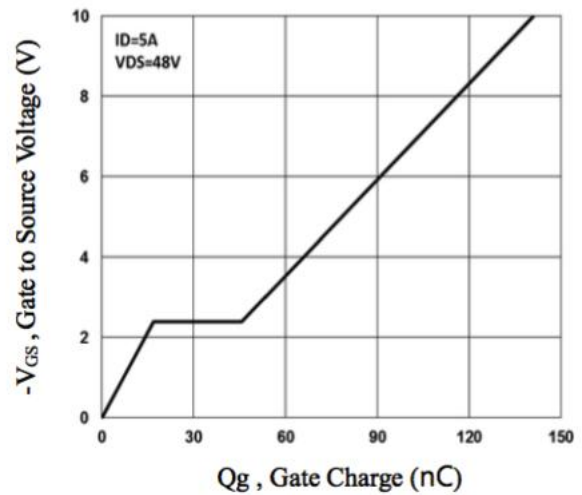


Fig.4 Gate Charge Waveform

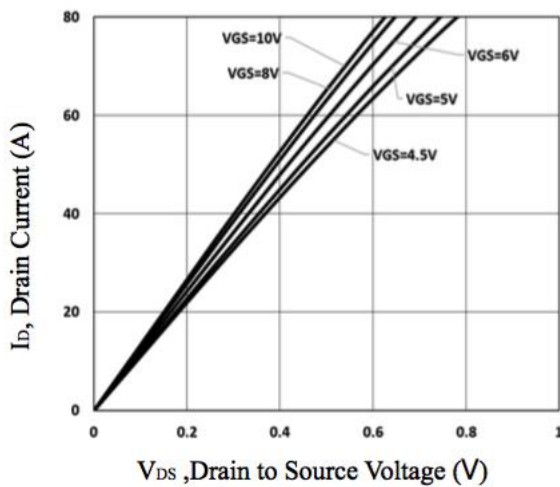


Fig.5 Typical Output Characteristics

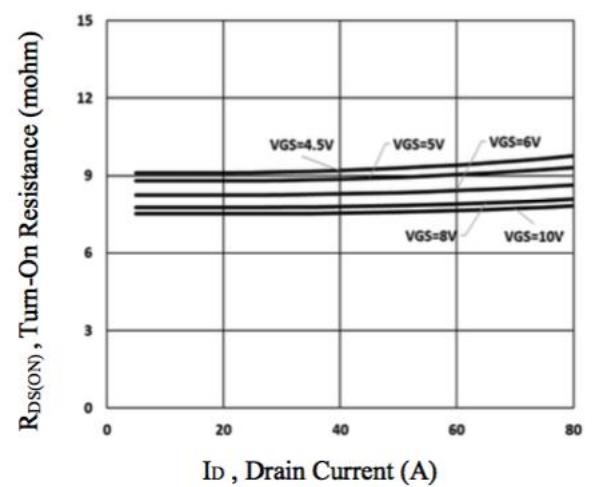


Fig.6 Turn-on Resistances vs. I_D



P-Ch 60V Fast Switching MOSFETs

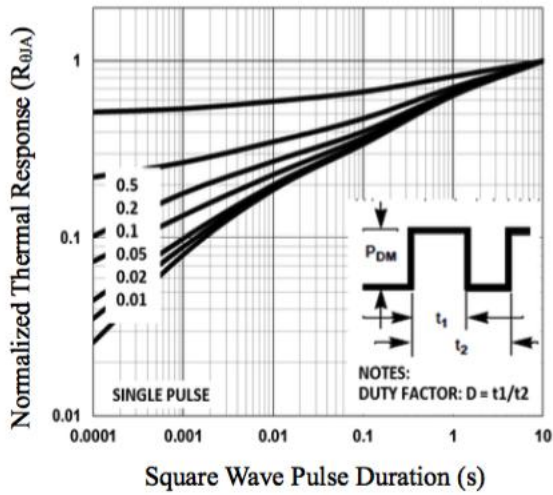


Fig.7 Normalized Transient Impedance

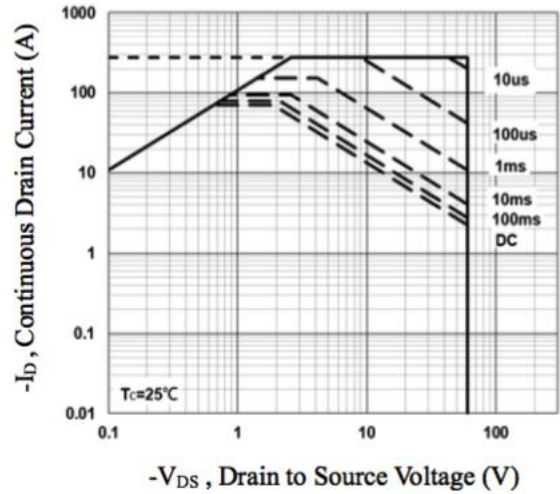


Fig.8 Maximum Safe Operation Area

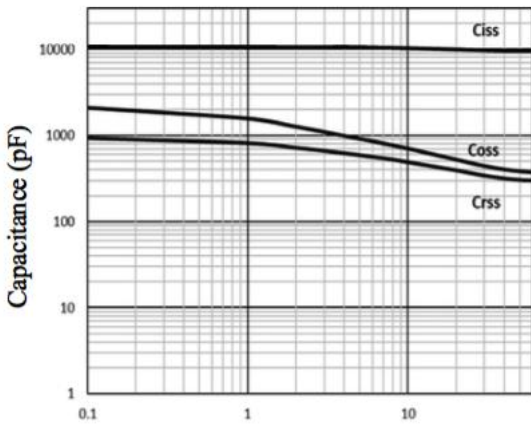


Fig.9 Capacitance Characteristics

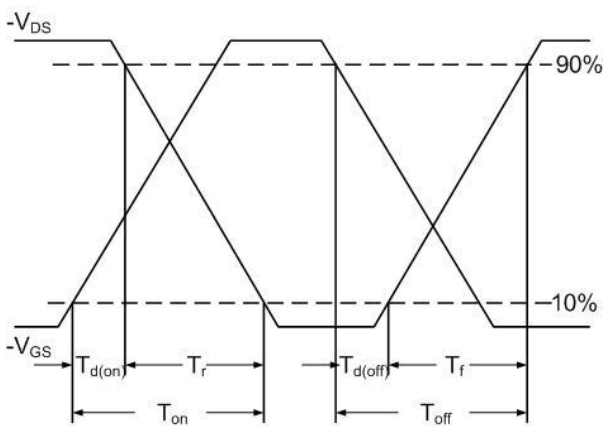


Fig.10 Switching Time Waveform

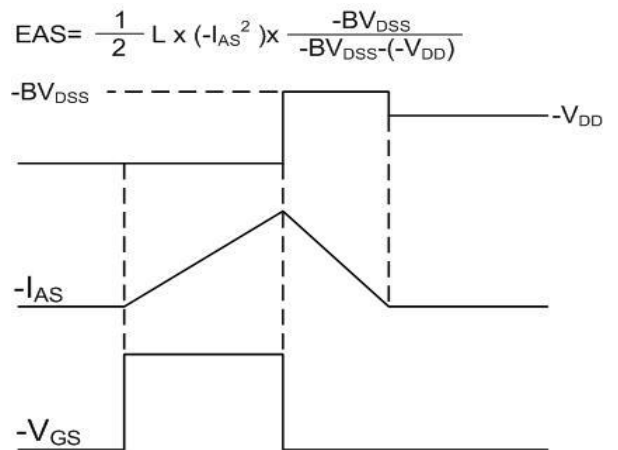
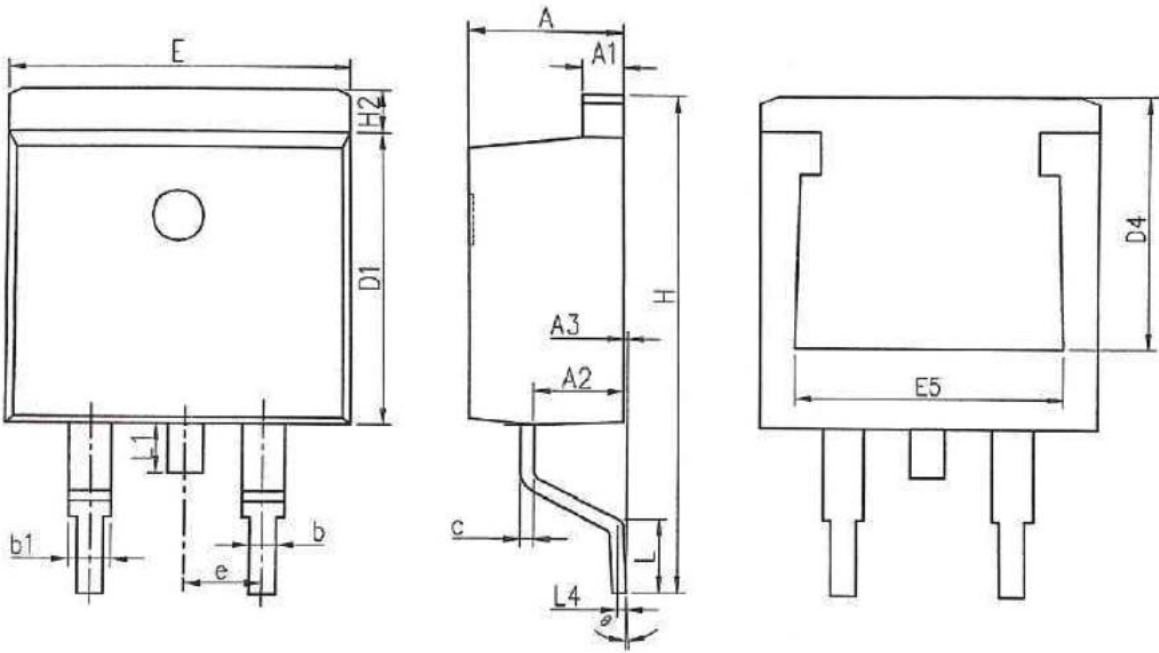


Fig.11 Unclamped Inductive Waveform



| SYMBOLS | MILLIMETERS | | INCHES | |
|---------|-------------|-------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.370 | 4.770 | 0.172 | 0.188 |
| A1 | 1.220 | 1.420 | 0.048 | 0.056 |
| A2 | 2.200 | 2.890 | 0.087 | 0.114 |
| A3 | 0.000 | 0.250 | 0.000 | 0.010 |
| b | 0.700 | 0.960 | 0.028 | 0.038 |
| b1 | 1.170 | 1.470 | 0.046 | 0.058 |
| c | 0.300 | 0.530 | 0.012 | 0.021 |
| D1 | 8.500 | 9.300 | 0.335 | 0.366 |
| D4 | 6.600 | - | 0.260 | - |
| E | 9.860 | 10.36 | 0.388 | 0.408 |
| E5 | 7.060 | - | 0.278 | - |
| e | 2.540 BSC | | 0.100 BSC | |
| H | 14.70 | 15.70 | 0.579 | 0.618 |
| H2 | 1.070 | 1.470 | 0.042 | 0.058 |
| L | 2.000 | 2.600 | 0.079 | 0.102 |
| L1 | 1.400 | 1.750 | 0.055 | 0.069 |
| L4 | 0.250 BSC | | 0.010 BSC | |
| Θ | 0° | 9° | 0° | 9° |